

ABSTRACT

A thermally conductive composition of the present invention contains metal particles (A) and a dispersion medium (B) in which the metal particles (A) are dispersed, wherein the metal particles (A) form a particle coupling structure by being sintered through a thermal treatment, the metal particles (A) have a particle size D_{50} at 50% in a volume-based cumulative distribution of equal to or greater than $0.8\text{ }\mu\text{m}$ and equal to or smaller than $5\text{ }\mu\text{m}$, and the metal particles (A) have a standard deviation of the particle size of equal to or less than $2.0\text{ }\mu\text{m}$.